



## **SPECIFICATION**

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10C030BB8NNNC
- Description : CAP, 3pF, 50V, ±0.1pF, C0G, 0603

A. Samsung Part Number

		<u>Cl</u> ①		C 030   3 4	<u>B</u> 5			<u>N</u> 8 9	<u>N</u> 10	<u>C</u> 10	
1	Series	Samsung Multi-layer Ceramic Capacitor									
2	Size	0603 (inch	code)	L:	1.6	6 ± 0.1	m	m	W:	0.8 ± 0.1	mm
3	Dielectric	C0G			8	Inner	electi	rode		Ni	
4	Capacitance	<b>3</b> pF				Termi	natio	n		Cu	
5	Capacitance	<b>±0.1</b> pF				Platin	g			Sn 100%	(Pb Free)
	tolerance				9	Produ	ıct			Normal	
6	Rated Voltage	50 V			10	Speci	al			Reserved for	future use
$\bigcirc$	Thickness	0.8 ± 0.1	mm		1	Packa	aging			Cardboard T	ype, 7" reel

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1M±±10% 0.5~5Vrms					
Q	460 min						
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	300% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	C0G						
Characterisitcs	(From -55 $^\circ\!\!\mathbb{C}$ to 125 $^\circ\!\!\mathbb{C}$ , Capacitance change shoud be within ±30PPM/ $^\circ\!\!\mathbb{C}$ )						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change :	Bending to the limit (1mm)					
	within $\pm 5\%$ or $\pm 0.5$ pF whichever is larger	with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to     Capacitance change :		Solder pot : 270±5℃, 10±1sec.					
Soldering heat	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger						
	Tan δ, IR : initial spec.						

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours $\times$ 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or $\pm 0.75$ pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 110 min						
	IR : 500Mohm or 25Mohm · μF						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or $\pm 0.3$ pF whichever is larger	Max. operating temperature					
	Q : 230 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm $\cdot \mu F$						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or $\pm 0.25$ pF whichever is larger	Min. operating temperature $\rightarrow$ 25 °C					
	Tan δ, IR : initial spec.	$\rightarrow$ Max. operating temperature $\rightarrow$ 25 °C					
5		5 cycle test					

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.